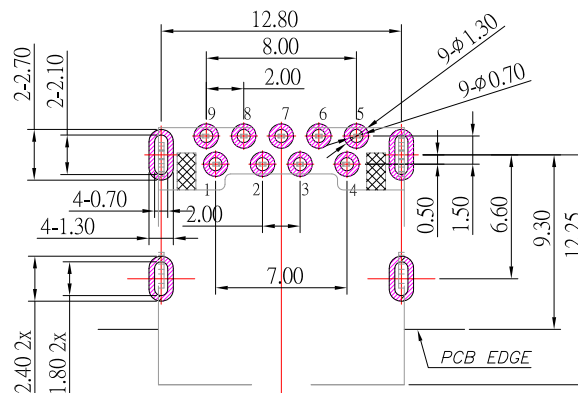




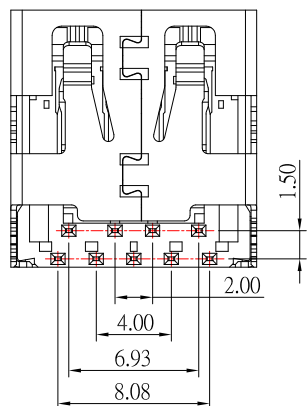
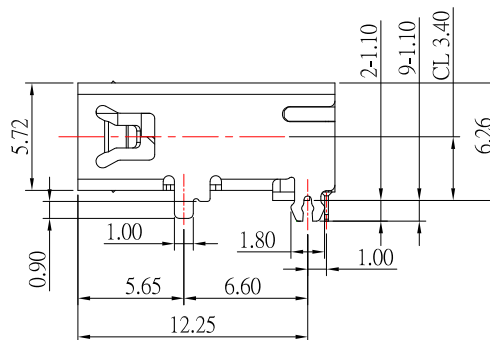
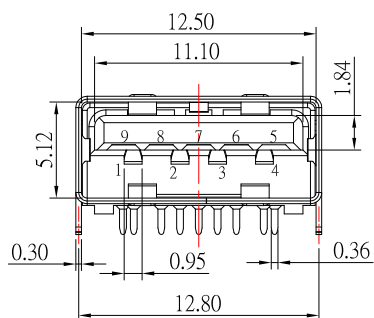
SUA-110H12-32x-S242

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"



RECOMMENDED PCB LAYOUT



**SPECIFICATIONS**

**Electrical:**

- 1.Contact Resistance: 30 mΩ Max
- 2.Insulation Resistance: 100 MΩ Min
- 3.Dielectric Withstanding Voltage: 100V AC
- 4.Insertion Force: 35N
- 5.Extraction Force: 10N

**Material:**

- 1.Housing: High-temp Plastic
- 2.Contact: Copper Alloy
- 3.Shell: SUS

**Finish:**

- 1.Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls  
Nickel under plated overall
- 2.Shell: Nickel under Plated surface layer

Pin #	SIGNAL NAME	DESCRIPTION	MATING SEQUENCE
1	VBUS	POWER	SECOND
2	D-	USB 2.0 DIFFERENTIAL PAIR	THIRD
3	D+		
4	GND	GROUND FOR POWER RETURN	SECOND
5	StdA_SSRX-	SUPERSPEED RECEIVER DIFFERENTIAL PAIR	LAST
6	StdA_SSRX+		
7	GND_DRAIN	GROUND FOR SIGNAL RETURN	
8	StdA_SSTX-	SUPERSPEED TRANSMITTER DIFFERENTIAL PAIR	
9	StdA_SSTX+		
Shell	Shield	CONNECTOR METAL SHELL	FRIST



TOLERANCE UNLESS OTHERWISE STATED :  
 Up to 5 ±0.2  
 Above 5 ~ 15 ±0.3  
 Above 15 ~ 30 ±0.4  
 Above 30 ~ 50 ±0.5  
 Angle ±0.3

3RD. ANGEL'S



UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	12/17/20			
CHECKED BY:	DATE	FINISH	MODLE	USB A/F 3.0 腳距6.6 H6.26mm L:13.7mm GEN 2
Jacky Chen	12/17/20			
APPROVED BY:	DATE	SCALE	DWG NO.	SUA-110H12-32x-S242
Tony Kao	12/17/20	1 : 1	PART NO.	SUA-110H12-32x-S242
		SHEET NO.	1 of 1	
				SIZE A4
				VER R1

1	更新料號	Jack	121720
ITEM NO.	DESCRIPTION	DRAWN	DATE